

03-22-2006



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PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)Rick Lee Tiefel 3-8-2006
Thomas Jay Newsom 3-13-2006Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No**3. Nature of conveyance/Execution Date(s):**

Execution Date(s) 3-8-2006 & 3-13-2006

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Joint Research Agreement
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other _____

2. Name and address of receiving party(ies)

Name: Sony Corporation

Internal Address: _____

Street Address: 7-35 Kitashinagawa, 6-Chome

Shinagawa-Ku

City: Tokyo

State: _____

Country: Japan

Zip: _____

Additional name(s) & address(es) attached? ☒ Yes ☐ No**4. Application or patent number(s):**☒ This document is being filed together with a new application.

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☐ No**5. Name and address to whom correspondence concerning document should be mailed:**

Name: Charles J. Kulas

Internal Address: TRELLIS INTELLECTUAL PROPERTY
LAW GROUP, PC

Street Address: 1900 Embarcadero Rd., Suite 109

City: Palo Alto

State: CA Zip: 94303

Phone Number: 650-842-0300

Fax Number: 650-842-0304

Email Address: _____

6. Total number of applications and patents involved: 1**7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00**

- ☐ Authorized to be charged by credit card
☐ Authorized to be charged to deposit account
☒ Enclosed
☐ None required (government interest not affecting title)

8. Payment Informationa. Credit Card Last 4 Numbers _____
Expiration Date _____

b. Deposit Account Number 50-3000

Authorized User Name Trellis Law Group

9. Signature:

Signature

March 14, 2006

Date

Brian N. Young, USPTO Reg. 48 602

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents: 5

Documents to be recorded (including cover sheet) should be faxed to (703) 306-5995, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

03/17/2006 CCHAU1 00000006 11375840

04 FC:8021

40.00 DP

PATENT
REEL: 017690 FRAME: 0759

2. Name and address of receiving party(ies)

Assignee Name:: Sony DADC US Inc.

Street of mailing address:: 1800 N Fruitridge Ave

City of mailing address:: Terre Haute

State or Province of mailing address:: IN

Country of mailing address:: USA

Postal or Zip Code of mailing address:: 47805

ASSIGNMENT

WHEREAS, I, as a below named inventor, am a sole inventor or a joint inventor of certain new and useful improvements in A **SPlicing ASSEMBLY AND METHOD** for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa, 6-Chome, Shinagawa-Ku, Tokyo, Japan and Sony DADC US Inc., an Indianan corporation with offices at 1800 N Fruitridge Ave., Terre Haute, IN, 47805, USA (hereinafter referenced as ASSIGNEES) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefore in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignees of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEES thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEES will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

And I hereby authorize and request my attorney(s) of record in this application to insert the execution date, serial number and filing date of this application in the spaces that follow: Serial Number: _____, Filing Date: _____.

This assignment is being executed on the date indicated below.

Date: 03-08-06

Inventor: *Rick Lee Tiefel*
Rick Lee Tiefel

Date: _____

Inventor: _____
Thomas Jay Newsom

ASSIGNMENT

WHEREAS, I, as a below named inventor, am a sole inventor or a joint inventor of certain new and useful improvements in A **SPLICING ASSEMBLY AND METHOD** for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa, 6-Chome, Shinagawa-Ku, Tokyo, Japan and Sony DADC US Inc., an Indianan corporation with offices at 1800 N Fruitridge Ave., Terre Haute, IN, 47805, USA (hereinafter referenced as ASSIGNEES) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefore in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignees of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEES thereof shall hereafter require and prepare at its own expense;

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This assignment is being executed on the date indicated below.

Date: _____

Inventor: _____

Rick Lee Tiesel

Date: 3-13-06

Inventor: *Thomas Jay Newsom*

Thomas Jay Newsom